

Title (en)

A METHOD FOR FORMING A SEMICONDUCTOR DEVICE WITH GATE SIDEWALL SPACERS OF SPECIFIC DIMENSIONS

Title (de)

VERFAHREN ZUR BILDUNG EINES HALBLEITERBAUELEMENTS MIT GATE-SEITENWAND-ABSTANDSELEMENTEN SPEZIFISCHER DIMENSIONEN

Title (fr)

FABRICATION D'UN DISPOSITIF SEMI-CONDUCTEUR A L'AIDE D'ESPACEURS DE DIMENSIONS SPECIFIQUES, POUR PAROIS LATERALES DE PORTES

Publication

EP 1829092 A2 20070905 (EN)

Application

EP 05852586 A 20051129

Priority

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- US 258604 A 20041203

Abstract (en)

[origin: WO2006060528A2] A method for forming spacers (22) of specific dimensions on a polysilicon gate electrode (20) protects the sidewalls (24) of the polysilicon gate electrode (20) during selective epitaxial growth. The spacers (22), whether asymmetric or symmetric, are precisely defined by using the same specific exposure tool (30-42), such as a 193 nm wavelength step and scan exposure tool, and the same pattern reticle (32), in both the defining of the polysilicon gate electrode pattern and the pattern spacer, while employing tight alignment specifications.

IPC 8 full level

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